



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Manufacturing Info/ Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	Cc Wu	Contact Title	Product Compliance Engineer		
Company Unique ID	1473	Response Date	2014-06-09	Contact Email	cc.wu@te.com				
Contact Phone Number	021-33259321								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	179955-2	Amount	1.561016	Version	-	Identity			
Manufacturer Item Name		Weight Uom	g	Mfr Site		Authority			
Date		UOM	Each						
EURoHS-0508	Product(s) meets EU RoHS requirement without any exemptions - true								
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products - true								
Manufacturing Information									
J-STD-020 MSL Rating		Max Total a Wave Time		Ramp Rate		Wave Additional Info			
Classification Temp		Max Wave Solder Time	0.0	Ramp Down Rate		Psi Rating Reflow			
Max Time Within 5		Psi Rating Wave		Package Designator		Size	0.0		
Time Above 217		Reflow Additional Info		Preheat Max Temp		Terminal Base Alloy	NAC		
Preheat Duration		bulk Solder Termination	NAC	Nbr or Reflow Cycles		Terminal Plating	NAC		
Preheat Min Temp		Nbr of Instances	0	Component Temp Spike		Shape	NAC		
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Material	1	Plating, Gold, Electrodeposited				1.0	1.22E-4	g	
Substance	2	Gold	Supplier	7440-57-5	99.7	1.0	1.2163E-4	g	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0506	0.3	1.0	3.66E-7	g	
Material	1	Plating, Nickel, Electrodeposited				1.0	0.008094	g	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	8.094E-6	g	
Substance	2	Nickel	Nickel	7440-02-0	99.8	1.0	0.00807781	g	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0506	0.1	1.0	8.094E-6	g	
Material	1	Copper-Nickel-Silicon Strip				1.0	1.5528	g	
Substance	2	Antimony	Supplier	7440-36-0	0.01	1.0	1.5528E-4	g	
Substance	2	Cobalt	Supplier	7440-48-4	0.1	1.0	0.0015528	g	
Substance	2	Tin	Supplier	7440-31-5	0.8	1.0	0.0124224	g	
Substance	2	Chromium	Supplier	7440-47-3	0.01	1.0	1.5528E-4	g	
Substance	2	Arsenic	Supplier	7440-38-2	0.015	1.0	2.3292E-4	g	
Substance	2	Zinc	Supplier	7440-66-6	1.5	1.0	0.023292	g	
Substance	2	Silicon	Supplier	7440-21-3	0.8	1.0	0.0124224	g	
Substance	2	Manganese	Supplier	7439-96-5	0.02	1.0	3.1056E-4	g	
Substance	2	Copper	Supplier	7440-50-8	93.9335	1.0	1.45859939	g	
Substance	2	Beryllium	Supplier	7440-41-7	0.0010	1.0	1.5528E-5	g	
Substance	2	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.01	1.0	1.5528E-4	g	

Substance	2	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	7.764E-6	g	
Substance	2	Nickel	Nickel	7440-02-0	2.7	1.0	0.0419256	g	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.0015528	g	